

REMARKS

Claims 1-28 are pending in the present application. Claims 1, 3, 5-7, 11-16, 19-21 and 26 have been amended. Claims 8-14, 16 and 22-28 have been withdrawn. Claims 29 and 30 have been canceled.

Election of Species

In the Response to Election Requirement dated February 22, 2006, Applicant asserted that claims 1-3, 15 and 17 are generic to the Species of Embodiments 1-9. Since the Examiner has not contested this assertion in the current Office Action dated May 11, 2006, Applicant presumes that the Examiner has conceded that claims 1-3, 15 and 17 are generic as asserted.

Priority Under 35 U.S.C. 119

Applicant notes the Examiner's acknowledgment of the Claim for Priority under 35 U.S.C. 119, and receipt of the certified copy of the priority document.

Drawings

Applicant respectfully notes the Examiner's acceptance of the drawings as filed along with the present application on April 13, 2004.

Enclosed are two (2) red-inked drawing Annotated Sheets. In Fig. 16, the semiconductor chips at the bottom of die pad section 200 have been respectively

denoted with reference numerals 400 and 500, as supported on page 27, lines 12-23 of the application. In Fig. 20, the topmost semiconductor chip has been denoted by reference numeral 400, as supported on page 34, lines 1-7 of the application. Also enclosed are two (2) drawing Replacement Sheets, incorporating the above noted drawing corrections. **The Examiner is respectfully requested to acknowledge receipt and acceptance of the drawing Replacement Sheets.**

Specification

The abstract has been corrected to remove reference numerals, as requested. The Examiner is therefore respectfully requested to withdraw the objection to the abstract. The title has been amended as "SEMICONDUCTOR DEVICE INCLUDING PLURAL CHIPS WITH PROTRUDING EDGES LAMINATED ON A DIE PAD SECTION", to be more clearly indicative of the invention to which the claims are directed. The Examiner is respectfully requested to approve the amended title, or in the alternative to suggest a more appropriate title.

Claim Rejections-35 U.S.C. 112

Claims 5-7 and 15-21 have been rejected under 35 U.S.C. 112, second paragraph, as being indefinite. Claims 5, 15 and 19 have been amended to be in better compliance with 35 U.S.C. 112, second paragraph. The Examiner is therefore respectfully requested to withdraw this rejection.

Claim Rejections-35 U.S.C. 102

Claims 1-4, 15, 17 and 18 have been rejected under 35 U.S.C. 102(b) as being anticipated by the Mess et al. reference (U.S. Patent Application Publication No. 2002/0195697). This rejection, insofar as it may pertain to the presently pending claims, is traversed for the following reasons.

The semiconductor device of claim 1 includes in combination a die pad section; a first semiconductor chip; a second semiconductor chip; lead terminal sections; and a resin encapsulating body "that seals the surface and the back surface of the die pad section, and the first and second semiconductor chips, wherein an edge portion of the second semiconductor chip protrudes from an edge portion of the first semiconductor chip, and an edge portion of the die pad section protrudes from the edge portion of the first semiconductor chip". Applicant respectfully submits that the Mess et al. reference as relied upon by the Examiner does not disclose these features.

The Examiner has primarily relied upon Fig. 12A of the Mess et al. reference. However, although Fig. 12A of the Mess et al. reference includes lead frame 94, an encapsulating enclosure is not shown specifically in any of Figs. 12A – 12C of the Mess et al. reference. In contrast, Fig. 13 of the Mess et al. reference for example illustrates encapsulating enclosure 84 as enclosing semiconductor dice 60A and 60B and a top surface of substrate 70. A die pad is not shown as encapsulated by resin in Fig. 13 of the Mess et al. reference. Also, a surface and a back surface of a die pad are not shown as encapsulated in Fig. 13 of the Mess et al. reference. Accordingly, Applicant

respectfully submits that the Mess et al. reference as relied upon by the Examiner does not include a resin encapsulating body as would be necessary to meet the features of claim 1. Applicant therefore respectfully submits that the semiconductor device of claim 1 distinguishes over the Mess et al. reference as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claims 1-4, is improper for at least these reasons.

The semiconductor device of claim 15 includes in combination a first semiconductor chip; a second semiconductor chip; a die pad section; lead terminal sections; and a resin encapsulating body "that seals the front and back surfaces of the die pad section, and the first and second semiconductor chips, wherein the fourth side of the second semiconductor chip protrudes from the second side of the first semiconductor chip".

Applicant respectfully submits that for at least somewhat similar reasons as set forth above, the Mess et al. reference does not include a resin encapsulating body that would be necessary to meet the features of claim 15. Applicant therefore respectfully submits that the semiconductor device of claim 15 distinguishes over the prior art as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claims 15, 17 and 18, is improper for at least these reasons.

Claim Rejections-35 U.S.C. 103

Claims 5-7 and 19-21 have been rejected under 35 U.S.C. 103(a) as being

unpatentable over the Mess et al. reference. Applicant respectfully submits that the Mess et al. reference as herein relied upon does not overcome the above noted deficiencies, and that this rejection is therefore improper for at least these reasons.

Conclusion

Applicant respectfully submits that claims 1-17, 15 and 17-21 should be allowable for at least the above reasons. Applicant also respectfully requests the Examiner to rejoin claims 8-14, 16 and 22-28, which should be found allowable at least by virtue of dependency upon generic claims 1 and 15 respectively.

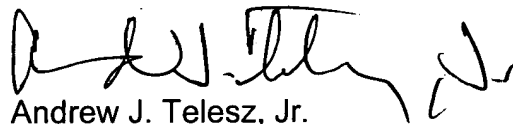
Accordingly, the Examiner is respectfully requested to reconsider and withdraw the corresponding rejections, and to pass all the claims of the present application to issue, for at least the above reasons.

In the event that there are any outstanding matters remaining in the present application, please contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (571) 283-0720 in the Washington, D.C. area, to discuss these matters.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment for any additional fees that may be required, or credit any overpayment, to Deposit Account No. 50-0238.

Respectfully submitted,

VOLENTINE FRANCOS & WHITT, P.L.L.C.

A handwritten signature in black ink, appearing to read 'Andrew J. Telesz, Jr.', with a stylized flourish at the end.

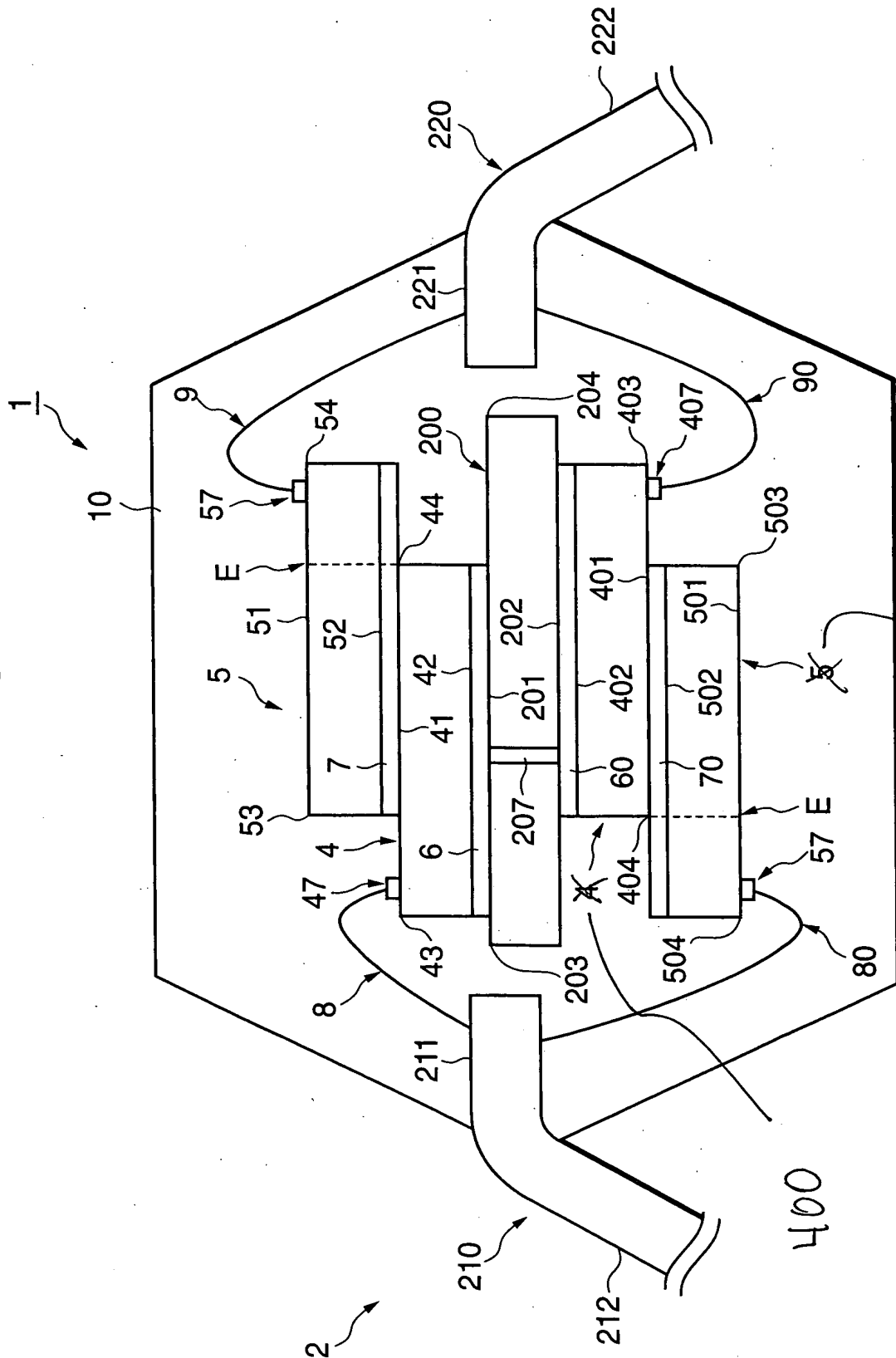
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Enclosures: Two (2) drawing Annotated Sheets
Two (2) drawing Replacement Sheets



Fig. 16



NOT AVAILABLE COPY

500

BEST AVAILABLE COPY

Fig.20

